L.N. 229 of 2006

PRODUCT SAFETY ACT
(CAP. 427)

Restriction of Use of Hazardous Substances in Electrical and Electronic Equipment (Amendment) (No. 2) Regulations, 2006

IN exercise of the powers conferred by articles 38 to 40 of the Product Safety Act, the Minister for Competitiveness and Communications, on the advice of the Malta Standards Authority, has made the following regulations:-

1. (1) The title of these regulations is the Restriction of Use of Hazardous Substances in Electrical and Electronic Equipment (Amendment) (No.2) Regulations, 2006 and they shall be read and construed as one with the Restriction of Use of Hazardous Substances in Electrical and Electronic Equipment Regulations, 2004, hereinafter referred to as "the principal regulations". Citation. L.N. 396 of 2004.

(2) These regulations shall apply from the 1st July 2006.

(3) These regulations implement the requirements of Commission Decision 2006/310/EC of 21 April 2006 amending, for the purposes of adapting to the technical progress, the Annex to Directive 2002/95/EC of the European Parliament and of the Council as regards exemptions for applications of lead.

2. For Schedule I of the principal regulations there shall be substituted the following:

"SCHEDULE I

(Regulation 4(2))

Applications of lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls (PBB) or polybrominated diphenyl ethers (PBDE) which are exempt from the requirements of regulation 4(2)

Item No.	Application
1.	Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.
2.	Mercury in straight fluorescent lamps for general purposes not exceeding: – halophosphate 10 mg – triphosphate with normal lifetime 5 mg – triphosphate with long lifetime 8 mg.
3.	Mercury in straight fluorescent lamps for special purposes.
4.	Mercury in other lamps not specifically mentioned in this Schedule.
5.	Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
6.	Lead as an alloying element in steel containing up to 0.35 % lead by weight, aluminium containing up to 0.4 % lead by weight and as a copper alloy containing up to 4 % lead by weight.
7.	(a) Lead in high melting temperature type solders (i.e. tin-lead solder alloys containing more than 85 % lead), (b) Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications, (c) Lead in electronic ceramic parts (e.g. piezoelectronic devices).
8.	Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC[3] amending Directive 76/769/EEC[4] relating to restrictions on the marketing and use of certain dangerous substances and preparations.

[3] OJ L 186, 12.7.1991, p. 59.
[4] OJ L 262, 27.9.1976, p. 201.

Item No.	Application

9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators.

9a. Deca BDE for polymeric applications.

9b. Lead in lead-bronze bearing shells and bushes.

10. ____

11. Lead used in compliant pin connector systems.

12. Lead as a coating material for the thermal conduction module c-ring.

13. Lead and cadmium in optical and filter glass.

14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight.

15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

16. Lead in linear incandescent lamps with silicate coated tubes.

17. Lead halide as radiant agent in High Intensity Discharge (HID) lamps used for professional reprography applications.

18. Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps when used as sun tanning lamps containing phosphors such as BSP (BaSi2O5:Pb) as well as when used as speciality lamps for diazo-printing reprography, lithography, insect traps, photochemical and curing processes containing phosphors such as SMS ((Sr,Ba)2MgSi2O7:Pb).

19. Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact Energy Saving Lamps (ESL).

20. Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCD).”.

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